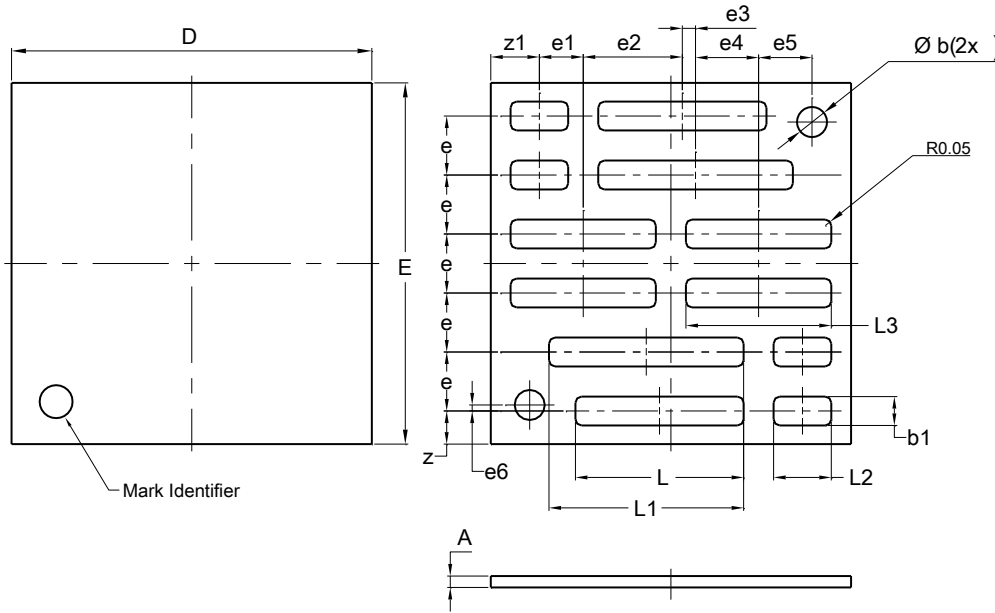


**Package Outline Dimensions**

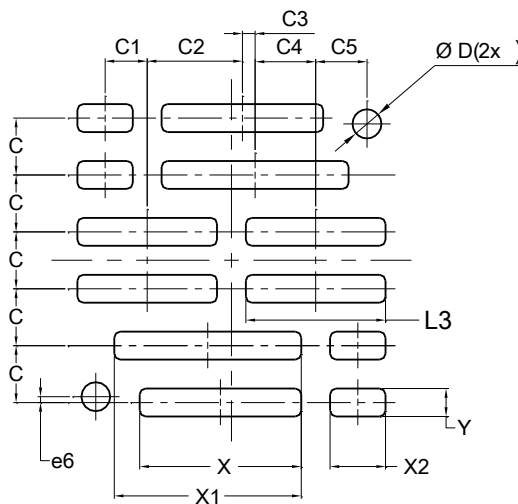
X4-DSN3030-14



X4-DSN3030-14			
Dim	Min	Max	Typ
A	0.050	0.150	0.100
bØ	0.220	0.280	0.250
b1	0.210	0.270	0.240
D	2.990	3.050	3.030
E	2.990	3.050	3.030
e	--	--	0.490
e1	--	--	0.365
e2	--	--	0.825
e3	--	--	0.110
e4	--	--	0.525
e5	--	--	0.445
e6	--	--	0.050
L	1.370	1.430	1.400
L1	1.590	1.650	1.620
L2	0.450	0.510	0.480
z	--	--	0.275
z1	--	--	0.405
All Dimensions in mm			

**Suggested Pad Layout**

X4-DSN3030-14



Dimensions	Value (in mm)
C	0.490
C1	0.365
C2	0.825
C3	0.110
C4	0.525
C5	0.445
C6	0.050
D	0.250
X	1.400
X1	1.620
X2	0.480
Y	0.240

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.